

BOARD LEVEL COOLING – Extruded 5330

Extruded 5330 is a series of dual radial board level heat sinks designed to cool TO-220 and TO-220-single gauge devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
533002B02551G	TO-220, TO-220-single gauge (0.020")
533101B02551G	TO-220, TO-220-single gauge (0.020")
533102B02551G	TO-220, TO-220-single gauge (0.020")



HEAT SINK DETAILS

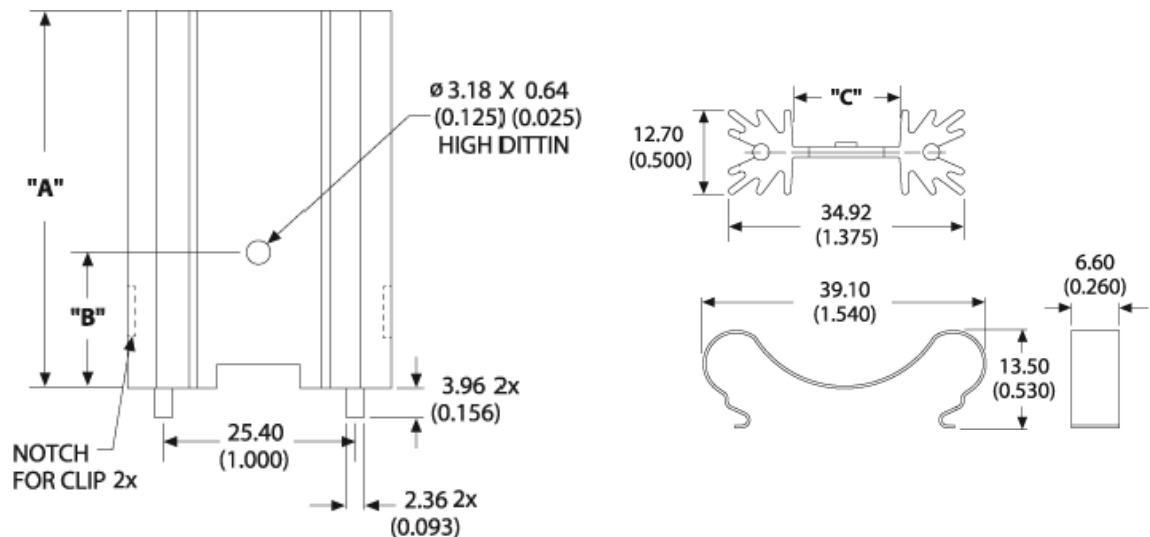
Property	Details
Material	Aluminum
Finishing	Black Anodize
Device Attachment Options	Kool Clip 51
Thermal Interface Material	N/A

Property	Details
Heat Sink Width (mm)	34.92
Heat Sink Height (mm)	See "A" Dim below
Heat Sink Length (mm)	12.70
Heat Sink Mounting Direction	Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

Part Number	"A" Dim	"B" Dim	"C" Dim	"X" Dim	"Y" Dim	"Z" Dim
533002B02551G	25.40	18.29	15.88	12.70 (0.500)	0.79 (0.031)	2.67 (0.105)
533101B02551G	38.10	21.59	17.20	12.70 (0.500)	0.79 (0.031)	2.67 (0.105)
533102B02551G	38.10	18.29	15.88	12.70 (0.500)	0.79 (0.031)	2.67 (0.105)



Board Level Cooling – Extruded 5330

Mounting Details:

